

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10591455
<b>Filing Date:</b>	18-Jan-2007
<b>Title of Invention:</b>	THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE COMPRISING THE SAME

<b>First Named Inventor/Applicant Name:</b>	Hideo Aoki
<b>Filer:</b>	Marvin Jay Spivak/Mimi Chanthaphone
<b>Attorney Docket Number:</b>	295958US0PCT

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	2	3	6
<b>Total in USD (\$)</b>				<b>1816</b>